



18/2822
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AMENDMENT TRANSMITTAL LETTER

Docket No.
SON-2050

Application No.
09/808,957-Conf. #5303

Filing Date
March 16, 2001

Examiner
M. Lewis

Art Unit
2822

Applicant(s): Hisao Hayashi

Invention: THIN FILM SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF

TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an amendment in the above-identified application.

The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	
Total Claims	25	- 27 =		x	
Independent Claims	3	- 3 =		x	
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					0.00

☒ Large Entity

☐ Small Entity

☒ No additional fee is required for this amendment.

☐ Please charge Deposit Account No. _____ in the amount of \$ _____.
A duplicate copy of this sheet is enclosed.

☐ A check in the amount of \$ _____ to cover the filing fee is enclosed.

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☒ Charge any additional filing or application processing fees required under 37 CFR 1.16 and 1.17.

Dated: October 22, 2004

Ronald P. Kananen
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Hisao HAYASHI

Confirmation No.: 5303

Application No.: 09/808,957

Art Unit: 2822

Filed: March 16, 2001

Examiner: M. Lewis

For: SUBSTRATE FOR INTEGRATING AND
FORMING A THIN FILM SEMICONDUCTOR
DEVICE THEREON (as amended)

AMENDMENT AFTER FINAL ACTION (37 C.F.R. SECTION 1.116)

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

INTRODUCTORY COMMENTS

In response to the Office Action dated July 28, 2004, please amend the above-identified U.S. patent application as follows:

Amendments to the Specification are reflected in the listing of claims which begins on page 2 of this paper.

Amendments to the Claims are reflected in the listing of claims which begins on page 4 of this paper.

Remarks/Arguments begin on page 11 of this paper.